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(54) **PACKAGE COMPONENT**

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(57) **ABSTRACT**

A package component includes a first substrate and a first conductive layer. The first substrate has a first surface and a second surface opposite to the first surface. The first conductive layer is disposed over the first surface of the first substrate. The first conductive layer includes a first conductive feature and a second conductive feature over the first conductive feature. The second conductive features covers a portion of the first conductive feature. A resistance of the second conductive feature is lower than a resistance of the second conductive feature. The first substrate includes a single-sided or a double-sided copper-clad laminate.

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